



# Material Composition Declaration

## EPC2040

Company Name	Efficient Power Conversion (EPC)	Issue Date:	9/22/2017
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	1.7 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	1.4610	86.1855	88.3774	861855
	Silicon oxide	7631-86-9	0.0063	0.3745		3745
	Silicon nitride	12033-89-5	0.0021	0.1239		1239
	Gallium nitride	25617-97-4	0.0076	0.4497		4497
	Aluminum	7429-90-5	0.0066	0.3881		3881
	Aluminum nitride	24304-00-5	0.0018	0.1074		1074
	Titanium	7440-32-6	0.0002	0.0147		147
	Titanium nitride	25583-20-4	0.0009	0.0550		550
	Copper	7440-50-8	0.0002	0.0128		128
	Tungsten	7440-33-7	0.0005	0.0311		311
	Polyimide		0.0108	0.6347		6347
Under Bump Metal	Titanium	7440-32-6	0.0001	0.0071	0.5976	71
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.0100	0.5905		5905
Solder Bump	Tin	7440-31-5	0.1785	10.5289	11.0251	105289
	Silver	7440-22-4	0.0075	0.4410		4410
	Copper	7440-50-8	0.0009	0.0551		551
Sum in total:			1.6952	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.